

Pollutant or pollutant property	Maximum for any 1 day	Maximum for monthly average
	Metric units—mg/off-kg of copper or copper alloy tumbled or burnished	
	English units—pounds per 1,000,000 off-pounds of copper or copper alloy tumbled or burnished	
Chromium	0.215	0.087
Copper	0.746	0.355
Lead	0.058	0.052
Nickel	0.320	0.215
Zinc	0.594	0.244
TTO	0.198	0.198
Oil and grease ¹	5.830	5.830

¹ For alternate monitoring.

(p) Subpart A—Surface Coating PSNS.

Pollutant or pollutant property	Maximum for any 1 day	Maximum for monthly average
	Metric units—mg/off-kg of copper or copper alloy surface coated	
	English units—pounds per 1,000,000 off-pounds of copper or copper alloy surface coated	
Chromium	0.274	0.111
Copper	0.951	0.453
Lead	0.074	0.066
Nickel	0.408	0.274
Zinc	0.757	0.312
TTO	0.252	0.252
Oil and grease ¹	7.430	7.430

¹ For alternate monitoring.

(q) Subpart A—Miscellaneous Waste Streams PSNS.

Pollutant or pollutant property	Maximum for any 1 day	Maximum for monthly average
	Metric units—mg/off-kg of copper or copper alloy formed	
	English units—pounds per 1,000,000 off-pounds of copper or copper alloy formed	
Chromium	0.008	0.003
Copper	0.027	0.013
Lead	0.0021	0.0019
Nickel	0.011	0.008
Zinc	0.022	0.009
TTO	0.007	0.007
Oil and grease ¹	0.218	0.218

¹ For alternate monitoring.

[48 FR 36957, Aug. 15, 1983; 48 FR 50719, Nov. 3, 1983]

§ 468.16 Effluent limitations representing the degree of effluent reduction attainable by the application of the best conventional pollution control technology (BCT). [Reserved]

Subpart B—Beryllium Copper Forming Subcategory

§ 468.20 Applicability; description of the beryllium copper forming subcategory.

This subpart applies to discharges of pollutants to waters of the United States, and introduction of pollutants into publicly owned treatment works from the forming of beryllium copper alloys.

[51 FR 7571, Mar. 5, 1986]

PART 469—ELECTRICAL AND ELECTRONIC COMPONENTS POINT SOURCE CATEGORY

Subpart A—Semiconductor Subcategory

Sec.

- 469.10 Applicability.
- 469.11 Compliance dates.
- 469.12 Specialized definitions.
- 469.13 Monitoring.
- 469.14 Effluent limitations representing the degree of effluent reduction attainable by the application of the best practicable control technology currently available (BPT).
- 469.15 Effluent limitations representing the degree of effluent reduction attainable by the application of the best available technology economically achievable (BAT).
- 469.16 Pretreatment standards for existing sources (PSES).
- 469.17 New source performance standards (NSPS).
- 469.18 Pretreatment standards for new sources (PSNS).
- 469.19 Effluent limitations representing the degree of effluent reduction attainable by the application of the best conventional pollution control technology (BCT).

Subpart B—Electronic Crystals Subcategory

- 469.20 Applicability.
- 469.21 Compliance dates.
- 469.22 Specialized definitions.
- 469.23 Monitoring.
- 469.24 Effluent limitations representing the degree of effluent reduction attainable

§ 469.10

by the application of the best practicable control technology currently available (BPT).

- 469.25 Effluent limitations representing the degree of effluent reduction attainable by the application of the best available technology economically achievable (BAT).
- 469.26 Pretreatment standards for existing sources (PSES).
- 469.27 New source performance standards (NSPS).
- 469.28 Pretreatment standards for new sources (PSNS).
- 469.29 Effluent limitations representing the degree of effluent reduction attainable by the application of the best conventional pollution control technology (BCT).

Subpart C—Cathode Ray Tube Subcategory

- 469.30 Applicability.
- 469.31 Specialized definitions.
- 469.32 Monitoring requirements.
- 469.34 Pretreatment standards for existing sources (PSES).
- 469.35 New source performance standards (NSPS).
- 469.36 Pretreatment standards for new sources (PSNS).

Subpart D—Luminescent Materials Subcategory

- 469.40 Applicability.
- 469.41 Specialized definitions.
- 469.42 New source performance standards (NSPS).
- 469.43 Pretreatment standards for new sources (PSNS).

AUTHORITY: Secs. 301, 304, 306, 307, 308, and 501 of the Clean Water Act (the Federal Water Pollution Control Act Amendments of 1972, as amended by the Clean Water Act of 1977, 33 U.S.C. 1311, 1314, 1316, 1317, 1318, and 1361; 86 Stat. 816, Pub. L. 92-500; 91 Stat. 1567, Pub. L. 95-217, unless otherwise noted.

SOURCE: 48 FR 15394, Apr. 8, 1983, unless otherwise noted.

Subpart A—Semiconductor Subcategory

§ 469.10 Applicability.

The provisions of this subpart are applicable to discharges resulting from all process operations associated with the manufacture of semiconductors, except sputtering, vapor deposition, and electroplating.

40 CFR Ch. I (7-1-04 Edition)

§ 469.11 Compliance dates.

The compliance deadline for the BAT fluoride limitation shall be as soon as possible as determined by the permit writer, but no later than November 8, 1985. The compliance deadline for the BAT and BCT limitations for total toxic organics (TTO) and pH, respectively, is as soon as possible as determined by the permit writer, but in no event later than July 1, 1984. The compliance date for PSES for TTO is July 1, 1984.

§ 469.12 Specialized definitions.

The definitions in 40 CFR part 401 and the chemical analysis methods in 40 CFR part 136 apply to this subpart.

In addition,

(a) The term “total toxic organics (TTO)” means the sum of the concentrations for each of the following toxic organic compounds which is found in the discharge at a concentration greater than ten (10) micrograms per liter:

1,2,4 Trichlorobenzene chloroform
1,2 Dichlorobenzene
1,3 Dichlorobenzene
1,4, Dichlorobenzene ethylbenzene
1,1,1 Trichloroethane methylene chloride
naphthalene
2 Nitrophenol phenol bis (2-ethylhexyl) phthalate tetrachloroethylene toluene trichloroethylene
2 Chlorophenol
2,4 Dichlorophenol
4 Nitrophenol pentachlorophenol di-n-butyl phthalate anthracene
1,2 Diphenylhydrazine isophorone butyl benzyl phthalate
1,1 Dichloroethylene
2,4,6 Trichlorophenol carbon tetrachloride
1,2 Dichloroethane
1,1,2 Trichloroethane dichlorobromomethane

(b) The term “semiconductors” means solid state electrical devices which perform functions such as information processing and display, power handling, and interconversion between light energy and electrical energy.

(c) The term “manufacture of semiconductors” means those processes, beginning with the use of crystal wafers, which lead to or are associated with the manufacture of semiconductor devices.

[48 FR 15394, Apr. 8, 1983, as amended at 48 FR 45250, Oct. 4, 1983]